

Ultraform® H 2320 006 AT Polyoxymethylene (POM)

Ultraform H 2320 006 AT is a POM with high molecular weight for injection molding.

Applications

Typical applications include thick-walled articles.

PHYSICAL	ISO Test Method	Property Value
Density, g/cm³	1183	1.41
Mold Shrinkage, parallel, %	294-4	2.1
Mold Shrinkage, normal, %	294-4	2.1
Moisture, %	62	
(50% RH)		0.2
(Saturation)		0.9
RHEOLOGICAL	ISO Test Method	Property Value
Melt Volume Rate (190 °C/2.16 Kg), cc/10min.	1133	2.9
MECHANICAL	ISO Test Method	Property Value
Tensile Modulus, MPa	527	
, -	9=1	
23°C	 -	2,600
23°C	527	2,600
23°C		2,600
23°C Tensile stress at yield, MPa		
23°C Tensile stress at yield, MPa 23°C	527	
23°C Tensile stress at yield, MPa 23°C Tensile strain at yield, % 23°C	527	62
23°C Tensile stress at yield, MPa 23°C Tensile strain at yield, %	527 527	62

IMPACT	ISO Test Method	Property Value
Izod Notched Impact, kJ/m ²	180	
-30°C		7
23°C		6.5
Charpy Notched, kJ/m ²	179	
-30°C		5.5
23°C		6.5
Charpy Unnotched, kJ/m ²	179	
-30°C		260
23°C		270
THERMAL	ISO Test Method	Property Value
Melting Point, °C	3146	165
HDT A, ° C	75	95
Coef. of Linear Thermal Expansion, Parallel, mm/mm °C		1.2 X10-4
	ISO Test Method	1.2 X10-4 Property Value
mm/mm °C	ISO Test Method IEC 60112	
mm/mm °C		Property Value
mm/mm °C ELECTRICAL Comparative Tracking Index	IEC 60112	Property Value 600
mm/mm °C ELECTRICAL Comparative Tracking Index Volume Resistivity (Ohm-m)	IEC 60112	Property Value 600 1E11
mm/mm °C ELECTRICAL Comparative Tracking Index Volume Resistivity (Ohm-m) Surface Resistivity (Ohm)	IEC 60112 IEC 60093 IEC 60093	Property Value 600 1E11 1E13
mm/mm °C ELECTRICAL Comparative Tracking Index Volume Resistivity (Ohm-m) Surface Resistivity (Ohm) Dielectric Constant (1 MHz)	IEC 60112 IEC 60093 IEC 60093 IEC 60250	Property Value 600 1E11 1E13 3.8
mm/mm °C ELECTRICAL Comparative Tracking Index Volume Resistivity (Ohm-m) Surface Resistivity (Ohm) Dielectric Constant (1 MHz) Dissipation Factor (1 MHz), E-4	IEC 60112 IEC 60093 IEC 60093 IEC 60250 IEC 60250	Property Value 600 1E11 1E13 3.8 50
ELECTRICAL Comparative Tracking Index Volume Resistivity (Ohm-m) Surface Resistivity (Ohm) Dielectric Constant (1 MHz) Dissipation Factor (1 MHz), E-4 UL RATINGS	IEC 60112 IEC 60093 IEC 60093 IEC 60250 IEC 60250 UL Test Method	Property Value 600 1E11 1E13 3.8 50 Property Value
mm/mm °C ELECTRICAL Comparative Tracking Index Volume Resistivity (Ohm-m) Surface Resistivity (Ohm) Dielectric Constant (1 MHz) Dissipation Factor (1 MHz), E-4 UL RATINGS Flammability Rating, 0.75mm	IEC 60112 IEC 60093 IEC 60093 IEC 60250 IEC 60250 UL Test Method UL94	Property Value 600 1E11 1E13 3.8 50 Property Value
ELECTRICAL Comparative Tracking Index Volume Resistivity (Ohm-m) Surface Resistivity (Ohm) Dielectric Constant (1 MHz) Dissipation Factor (1 MHz), E-4 UL RATINGS Flammability Rating, 0.75mm Relative Temperature Index, 0.75mm	IEC 60112 IEC 60093 IEC 60093 IEC 60250 IEC 60250 UL Test Method UL94	Property Value 600 1E11 1E13 3.8 50 Property Value HB

Mechanical w/o Impact, °C		90
Mechanical w/ Impact, °C		90
Electrical, °C		105
Flammability Rating, 3.0mm	UL94	НВ
Relative Temperature Index, 3.0mm	UL746B	
Mechanical w/o Impact, °C		105
Mechanical w/ Impact, °C		90

Processing Guidelines

Material Handling

Max. Water content: 0.15%

Product is supplied in polyethylene bags and drying prior to molding is not required. However, after relatively long storage or when handling material from previously opened containers, preliminary drying is recommended in order to remove any moisture which has been absorbed. If drying is required, a dehumidifying or desiccant dryer operating at 80 - 110°C (176 - 230°F) is recommended. Drying time is dependent on moisture level, however 2-4 hours is generally sufficient. Further information concerning safe handling procedures can be obtained from the Safety Data Sheet. Alternatively, please contact your BASF representative.

Typical Profile

Melt Temperature 190-230°C (375-446°F) Mold Temperature 60-120°C (140-248°F) Injection and Packing Pressure 35-70 bar (500-1000psi)

Mold Temperatures

A mold temperature of 60-120°C (140-248°F) is recommended, however temperatures of as low as 45°C (113°F) can be used where applicable.

Pressures

Injection speed must be optimized. A filling rate which is too high results in anisotropic mechanical properties, while a filling rate which is too low yields parts with poor surface finish. The tool must be vented to avoid burn marks and prevent mold deposits. Injection pressure controls the filling of the part and should be applied for 90% of ram travel. Packing pressure affects the final part and can be used effectively in controlling sink marks and shrinkage. It should be applied and maintained until the gate area is completely frozen off.

Back pressure can be utilized to provide uniform melt consistency and reduce trapped air and gas.

Fill Rate

Injection speed must be optimized. A filling rate which is too high results in anisotropic mechanical properties, while a filling rate which is too low yields parts with poor surface finish. The tool must be vented to avoid burn marks and prevent mold deposits.

Note

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